Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	(("6162743") or ("20010004550")). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/09 10:04
S1	7842	plasma adj chamber	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 14:31
S2	950794	(o or oxygen) same (he or helium)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 14:32
S3	310245	(circuit elecronic) adj (board component)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 14:33
S4	102	S1 and S2 and S3	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 14:35
S5	1107990	electrode	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 14:36
S6	948	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 14:36
S7	714	S6 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 14:36
S8	170	S7 and facing	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 17:53
S9	1997	glow adj discharge adj plasma	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 15:22
S10	1361245	resin	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 15:22

S11	455	S9 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 15:25
S12	7397	fukuoka.in.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 15:25
S13	71	S12 and plasma	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 15:27
S14	22334	flip-chip flip adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 15:41
S15	22334	"flip-chip" flip adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO	OR .	ON	2005/10/24 15:41
S16	3139	S15 and plasma	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 15:42
S17	8	S16 and S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 15:48
S18	4	S1 and S15 and underfill same resin	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/03/01 17:29
S19	1	"5156997".PN.	USPAT; USOCR	OR	OFF	2005/10/24 15:53
S20	12	(("5457356") or ("5668059") or ("5768108") or ("5841197") or ("5865365") or ("5888884") or ("5956605") or ("5998228") or ("5998232") or ("6002163") or ("6015722") or ("6063647")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 15:55
S21	1	S20 and (He or helium)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 16:24
S22	860	S2 and plasma adj etch	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 16:24

S23	133	S2 same plasma adj etch	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 16:54
S24	130172	improved same resin	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 16:55
S25	5408	S24 and plasma	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 16:55
S26	274	S25 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 16:55
S27	1	S26 and S14	US-PGPUB; USPAT; USOCR; EPO; JPO	OR ·	OFF	2005/10/24 17:17
S28	11256	surface adj modification	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 17:17
S29	94	S28 and S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 17:52
S30	0	S14 and S2 same S28	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 17:53
S31	1	S28 and S2 and S14	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/10/24 18:12
S32	2	(("6723627") or ("6306683")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2005/10/24 18:12
S33	0	(2004/0157170).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/01 17:29
S34	1	("20040157170").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/01 17:29

S35	2	(("6,306,683") or ("5,922,470")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 12:00
S36	1	polyimide and S35	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 12:31
S37	2	resin and S35	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 14:48
S38	18109	composition adj ratio	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 14:48
S39	360	composition adj ratio with (c or carbon) with (Si silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 14:49
S40	289	S39 and layer	US-PGPUB; USPAT; USOCR; EPO; JPO	OR .	OFF	2006/03/08 14:50
S41	1	Sichn and S39	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 14:50
S42	3	Sich and S39	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 17:46
S44	109	c/si adj ratio	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 17:58
S45	140	c/si adj ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:24
S46	1	("20040152334").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/03/08 18:15

S47	1	sichn and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:22
S48	4	sich and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:22
S49	229	c/si near2 ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:25
S50	1	sichn and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:25
S51	243	c/si near3 ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:25
S52	283	c/si with ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/08 18:26
S53	1	sichn and S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 10:04